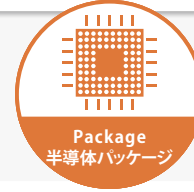


## Capillary Underfill(CUF) Semiconductor encapsulation materials キャピラリーアンダーフィル対応 半導体封止材



### Applications 用途

High-density Advanced IC Packages(BGA, CSP, etc.)  
高密度先端半導体パッケージ (BGA、CSP など)



Capillary underfill material with reduced void, that realizes underfilling to the narrow gap and pitch by high fluidity  
高流動性で狭ギャップ / 狭ピッチの実装に対応する、低ボイドキャピラリーアンダーフィル材料

High fluidity  
高流動性

Excellent fillability for  
Narrow gap/pitch  
狭ギャップ/ピッチ充填

Reduced void/bleed  
低ボイド/低ブリード

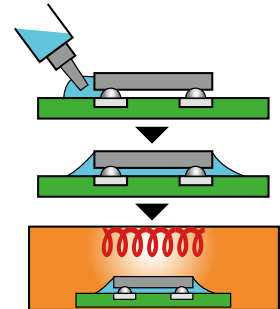
### Line-up

ラインアップ

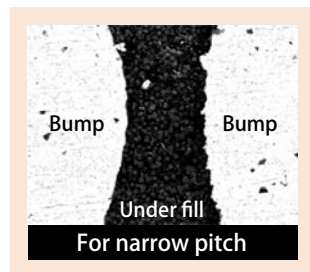
Conventional

- 1 Compatible with narrow gap
- 2 Uniform penetration
- 3 High-speed fillability
- 4 Compatible with low-k film
- 5 High moisture reflow resistance

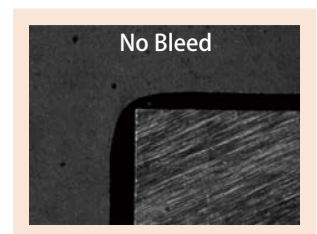
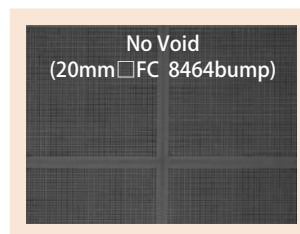
Part Number	Features
CV5300	High fluidity
CV5350	Short-time curing



### Excellent fillability for Narrow gap/pitch 狭ギャップ/ピッチ充填



### Reduced void/bleed 低ボイド/低ブリード



### General properties 一般特性

Item	Unit	CV5300	CV5350
Filler size Max	μm	1	5
C.T.E.	ppm/°C	33	30
Tg (TMA)	°C	110	150
Modulus	GPa	7	10

The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。